File View Edit Tools Window Help

- (39) "0104653"
- (0) 2003/0104653
- (0) 10/82865
- (0) 10/829851
- (2) 5744827.pn.
- (1) 09/944246
- (2857) stack$2 adj (package chip)
- (2) 5744827.pn.
- (0) 09/944246 and 5744827.pn.
- (3) 09/944246 5744827.pn.
- (1336674) lead
- (66066) wire near bond$4
- (15744) lead near6 (wire near bond$4)
- (53) (stack$2 adj (package chip)) same (lead near6 (wire near bond$4))
- (133623) samsung.as.
- (41120) cho.in.
- (7373) samsung.as. and cho.in.
- (1) ((stack$2 adj (package chip)) and (lead near6 (wire near bond$4))) and (samsung.as. and
- (20) ((stack$2 adj (package chip)) and (lead near6 (wire near bond$4))) and samsung.as.
- (276) (stack$2 adj (package chip)) and (lead near6 (wire near bond$4))
- (1) KR2001028815

Favorites
Tagged (35)
UDC
Queue
Trash

Browse | Queue | Clear

QBs | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | Plurals

Default operator: OR | Highlight all hit terms initially

(stack$2 adj (package chip)) and (lead near6 (wire near bond$4))

Feb. 2004

	U		Inventor	Document ID	Issue D	Pg	Title	Current O	Current XRef	Retrieval Cl	S	C	P		J			Image Doc. ID	P
1			Horiuchi, Michio	US 20020031	200203	17	Semiconductor device and process of production of sa	438/125	257/E23.004;									US 20020031	
2			Park, Sang Woo	US 6137162 A	200010	12	Chip stack package	257/685	257/686;									US 6137162	
3			Ahn, Kie Y. et al.	US 20010033	200110	10	Stacked integrated circuits	365/63										US 20010033	
4			Ahn, Kie Y. et al.	US 6395630 B	200205	11	Stacked integrated circuits	438/667	257/673;									US 6395630	
5			Ahn, Kie Y. et al.	US 6314013 B	200111	11	Stacked integrated circuits	365/63	257/737;									US 6314013	
6			Ahn, Kie Y. et al.	US 6122187 A	200009	11	Stacked integrated circuits	365/63	257/673;									US 6122187	
7			Ahn, Sang-Ho et	US 20020121	200209	24	Ultra-thin semiconductor package device and method f	257/666	257/678;									US 20020121	
8			Akasaki, Hidehik	US 5861670 A	199901	11	Semiconductor device package	257/737	257/700;									US 5861670	

Ready

NUM